



1/7

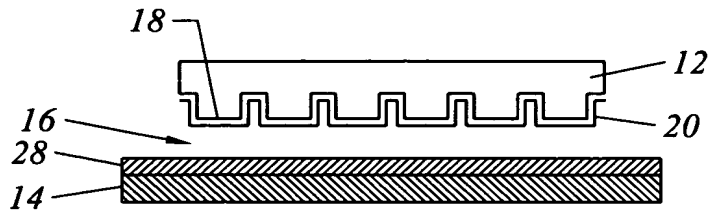


FIG. 1A

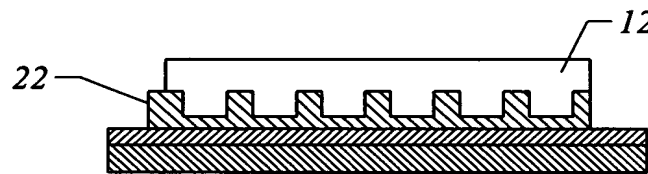


FIG. 1B

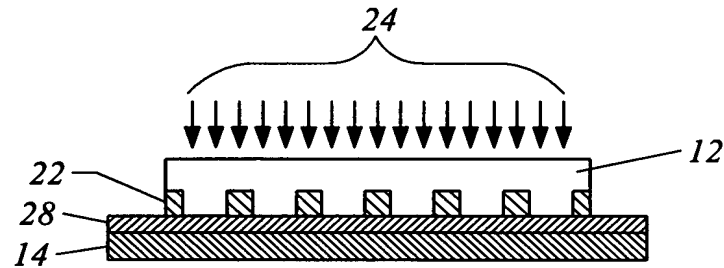


FIG. 1C

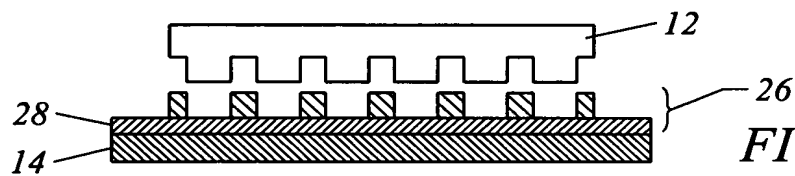


FIG. 1D



FIG. 1E

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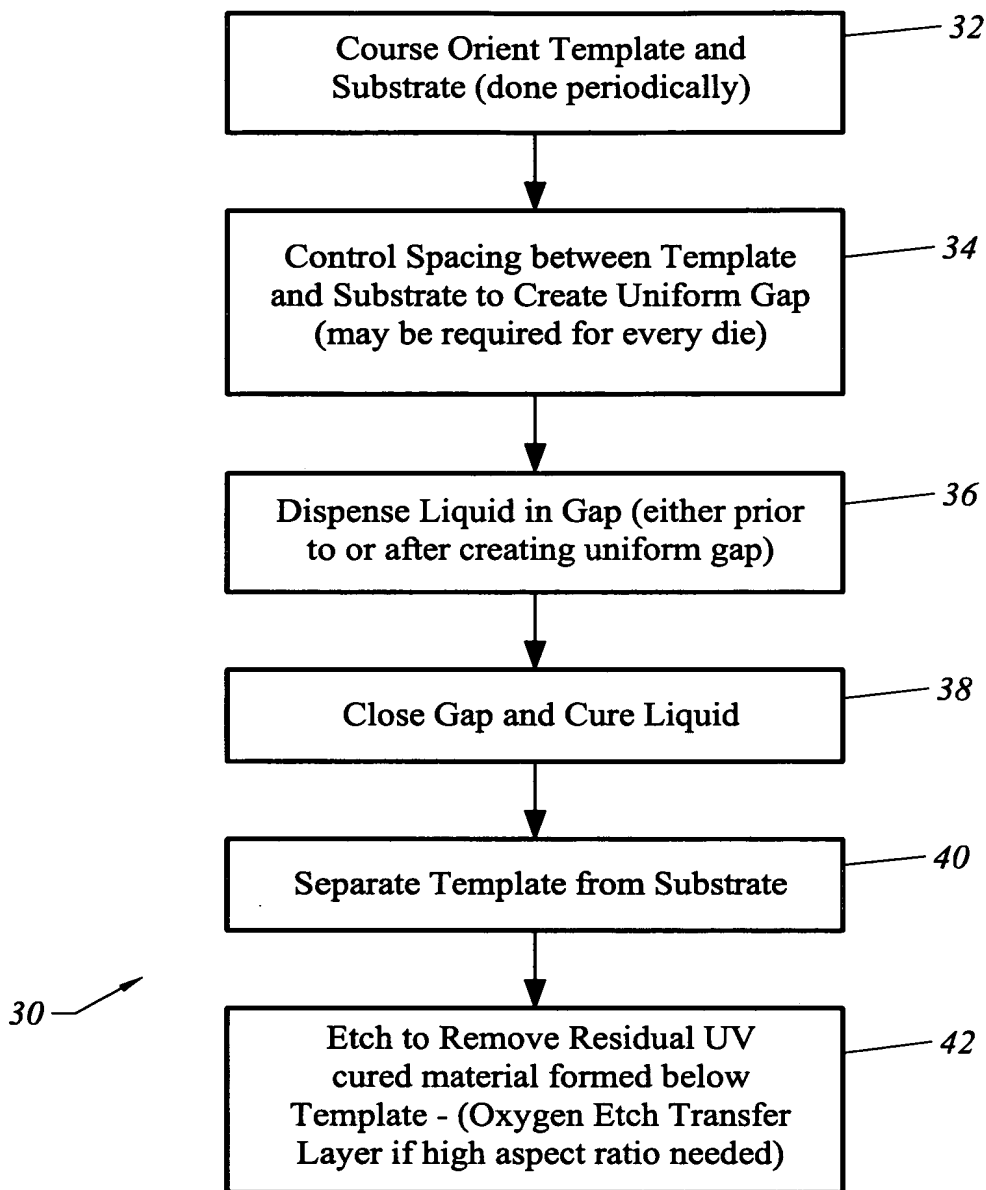


FIG. 2

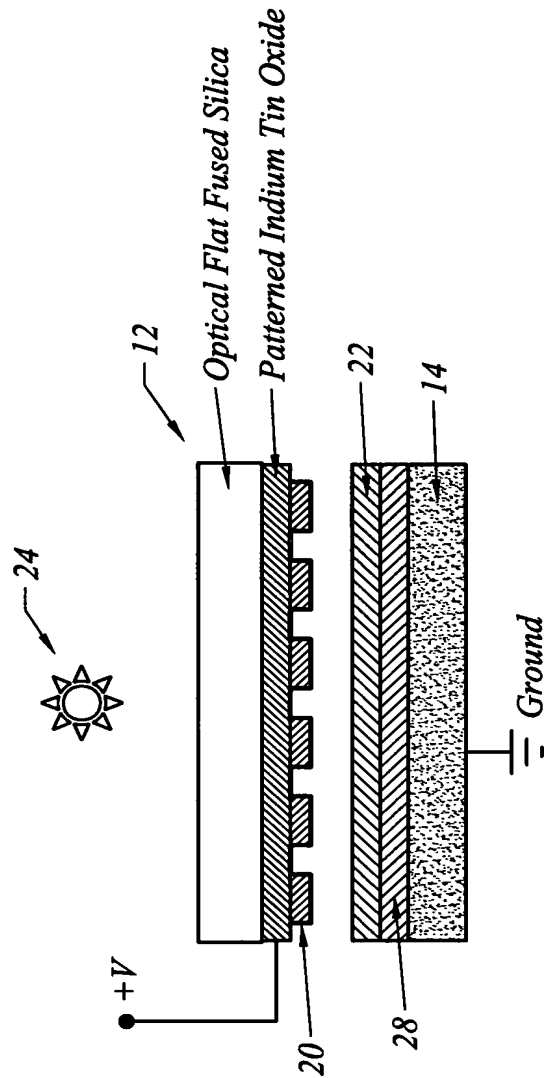
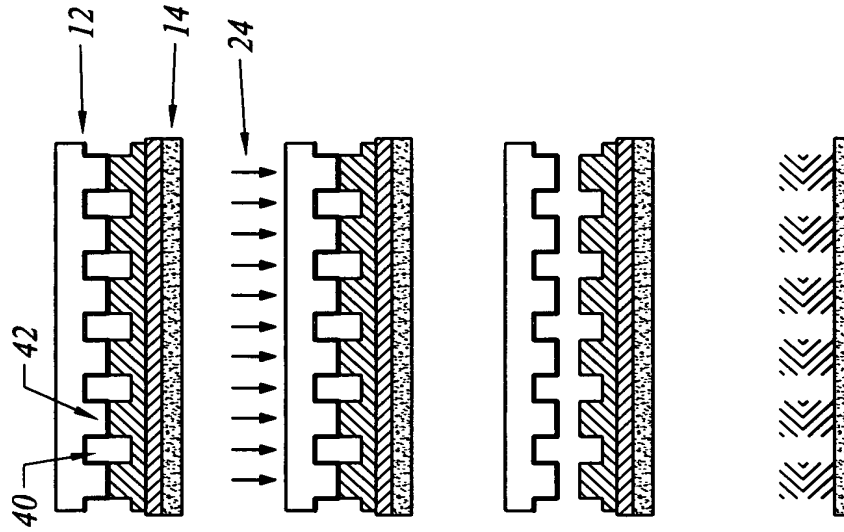


FIG. 3

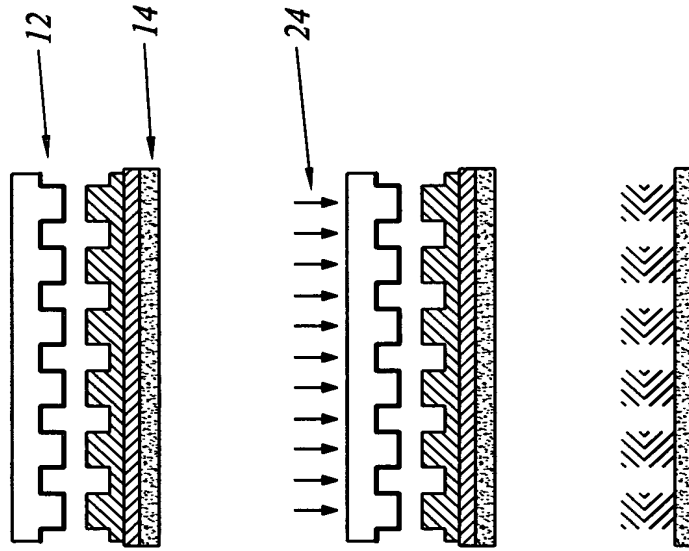


- Apply electric field and maintain uniform gap to induce the liquid to adhere to the template
- UV cure the liquid
- Separate the template from the substrate
- Etch to break-through UV cured liquid, followed by RIE etch transfer into transfer layer to obtain high-aspect ratio structure

FIG. 4



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- Apply electric field and maintain uniform gap to induce the liquid to be attracted to the template without making contact
- UV cure the liquid
- Etch to break-through UV cured liquid, followed by RIE etch transfer into transfer layer to obtain high-aspect ratio structure

FIG. 5



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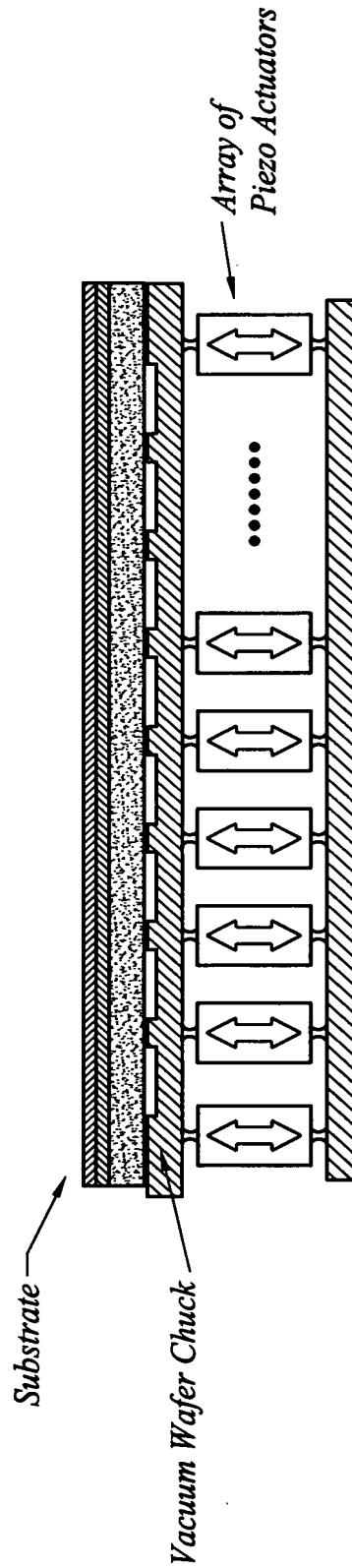


FIG. 6



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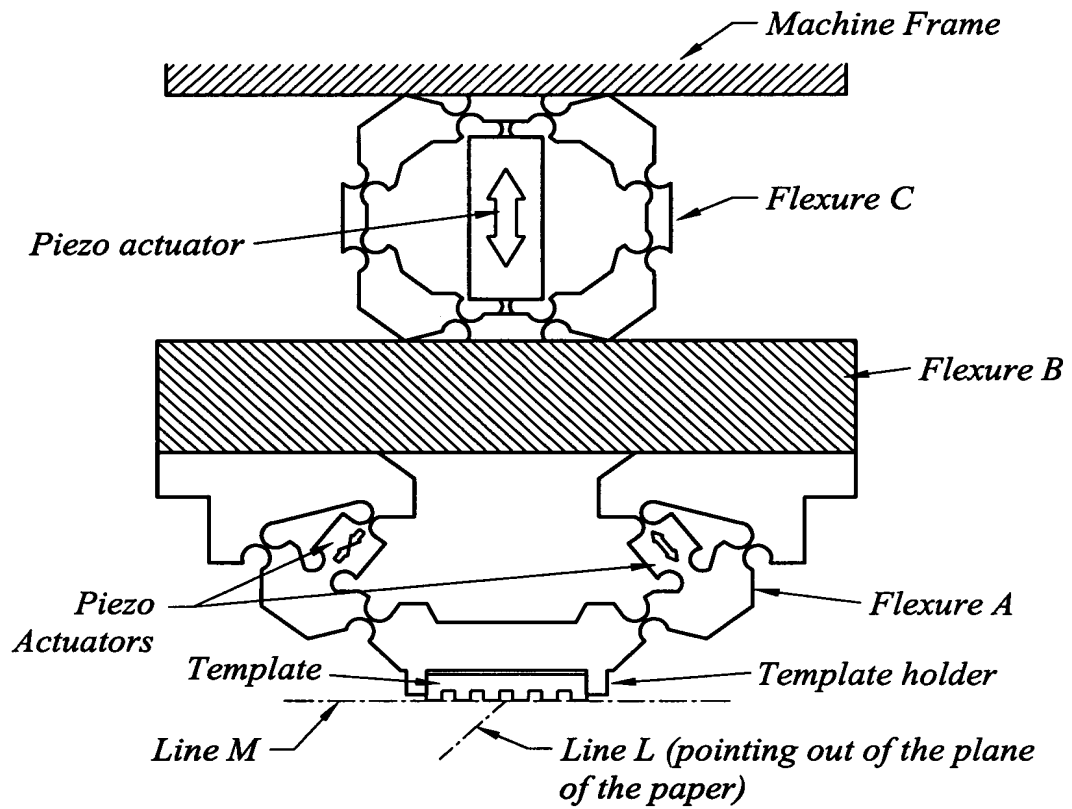


FIG. 7